Special Issue

Additive Manufacturing: Technology, Challenges and Applications

Message from the Guest Editor

This Special Issue focuses on recent advances in additive manufacturing processes, applications and technologies. There is a growing need to know determine the new industrial applications of AM, and identify the new materials that are being applied in the field. It is necessary to discover what the future trends of new technologies are. Each technology and each application sector present needs that must be considered, from the part's design, to the processing conditions of the same. Original research papers and review articles are invited for this Special Issue. Dr. Santiago Ferrandiz

Guest Editor

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